

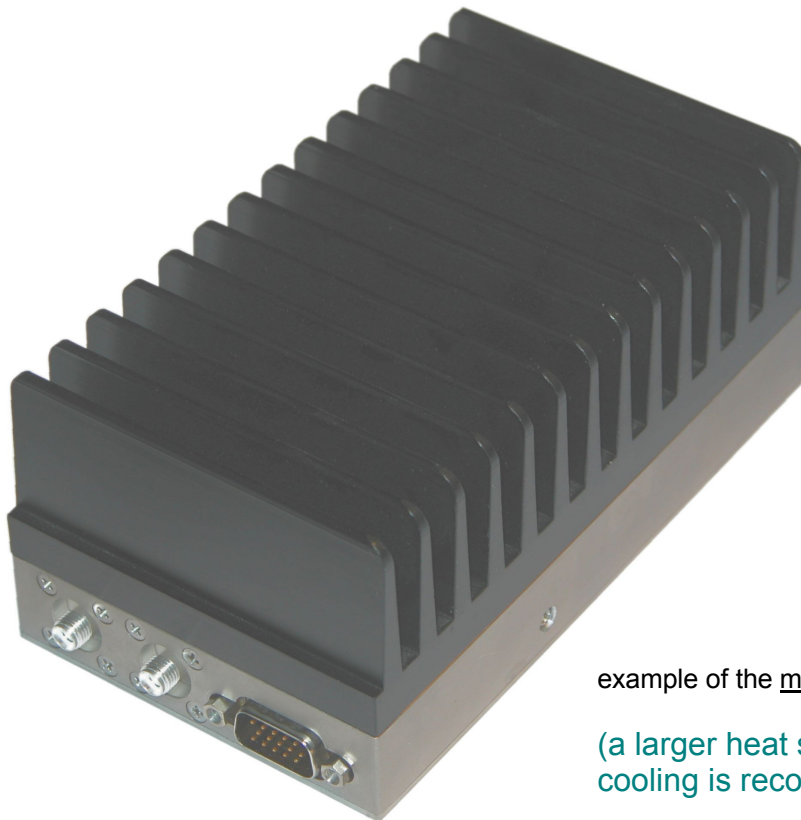
RF POWER AMPLIFIER

**BSU**

cooling instructions

## VERY IMPORTANT !

- ▶ The device must be cooled adequately !
- ▶ The device must be mounted on a heat sink.
- ▶ A thermal compound between module and heat sink is obliged for low thermal contact resistance.
- ▶ Heat sink flatness should be less than 100  $\mu\text{m}$   
(a heat sink that is not flat or particles between module and heat sink may cause too much mechanical stress)



example of the minimum required heat sink

(a larger heat sink or forced air cooling is recommended)

- ▶ If you operate the device without adequate cooling the reliability will be drastically reduced. Please do not underestimate the produced dissipation heat !

Ordering Code: BSU-HS1 = Heatsink for BSU with mounting accessories kit